SWITCHMODE™ Schottky Power Rectifier TO247 Power Package

This device employs the Schottky Barrier principle in a large area metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Highly Stable Oxide Passivated Junction
- Guardring for Overvoltage Protection
- Low Forward Voltage Drop
- Dual Diode Construction; Terminals 1 and 3 May Be Connected for Parallel Operation at Full Rating.
- Full Electrical Isolation without Additional Hardware
- Pb-Free Package is Available*

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 4.3 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	15	٧
Average Rectified Forward Current	Io	20	Α
(At Rated V _R , T _C = 120°C) Per Leg Per Package		20 40	
Peak Repetitive Forward Current, (At Rated V_R , Square Wave, 20 kHz, $T_C = 95^{\circ}C$) Per Leg	I _{FRM}	40	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) Per Package	I _{FSM}	120	A
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-55 to +150	°C
Voltage Rate of Change, (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs

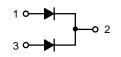
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

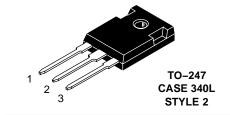


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SCHOTTKY BARRIER RECTIFIER 40 AMPERES, 15 VOLTS





MARKING DIAGRAM



MBR4015LWT = Specific Device Code = Assembly Location Α

Υ = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
MBR4015LWT	TO-247	30 Units / Rail
MBR4015LWTG	TO-247 (Pb-Free)	30 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

THERMAL CHARACTERISTICS

Rating		Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	Per Leg	$R_{ heta JC}$	0.57	°C/W
Junction-to-Ambient	Per Leg	R_{\thetaJA}	55	

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 2), See Figure 2 Per Leg		T _J = 25°C	T _J = 100°C	V
$(I_F = 20 \text{ A})$ $(I_F = 40 \text{ A})$		0.42 0.50	0.36 0.48	
Maximum Instantaneous Reverse Current (Note 2), See Figure 4 Per Leg	I _R	T _J = 25°C	T _J = 100°C	mA
$(V_R = 15 \text{ V})$ $(V_R = 7.5 \text{ V})$		5.0 2.7	530 370	

- 1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.
- 2. Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2%.

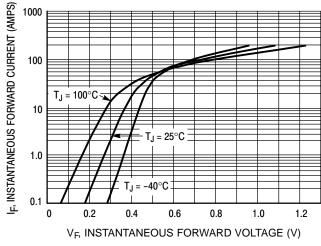


Figure 1. Typical Forward Voltage Per Leg

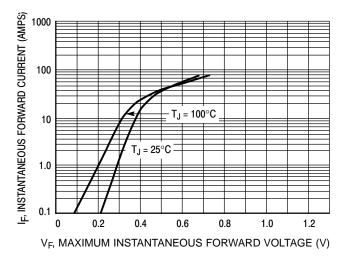


Figure 2. Maximum Forward Voltage Per Leg

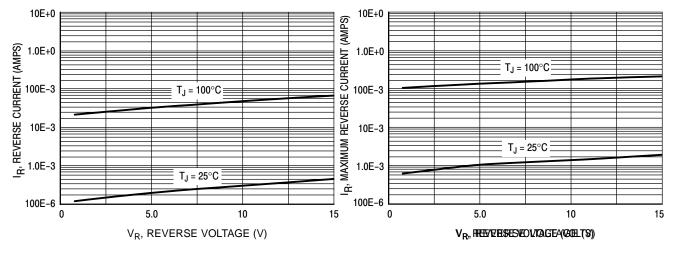
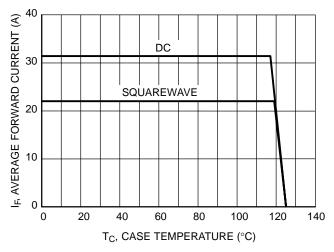


Figure 3. Typical Reverse Current Per Leg

Figure 4. Maximum Reverse Current Per Leg

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P_{FO}, AVERAGE POWER DISSIPATION (WATTS) $I_{pk}/I_0 = \pi$ WAVE 12 $I_{pk}/I_0 = 5$ $I_{pk}/I_0 = 10$ 10 $I_{pk}/I_0 = 20$ 8.0 6.0 4.0 2.0 0 5.0 10 20 25 30 35 IO, AVERAGE FORWARD CURRENT (A)

SQUARE

Figure 5. Current Derating Per Leg

Figure 6. Forward Power Dissipation Per Leg

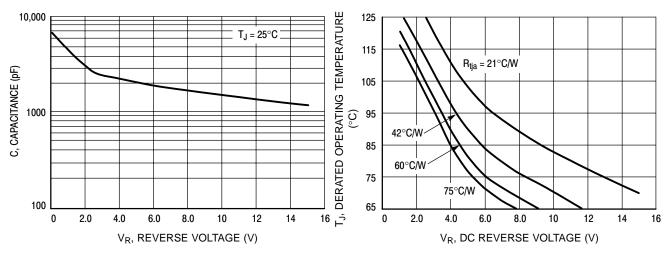


Figure 7. Capacitance Per Leg

Figure 8. Typical Operating Temperature Derating Per Leg*

^{*}Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - T_{Jmax}$ r(t)Pr, where r(t) = Rthja. For other power applications further calculations must be performed.

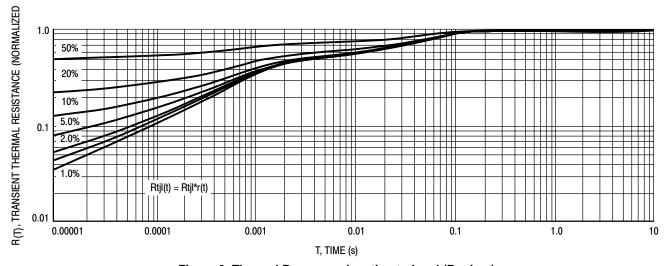


Figure 9. Thermal Response Junction to Lead (Per Leg)

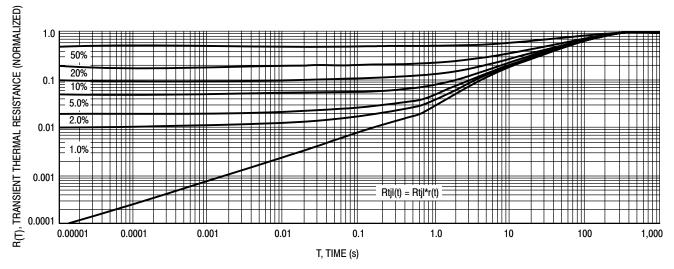
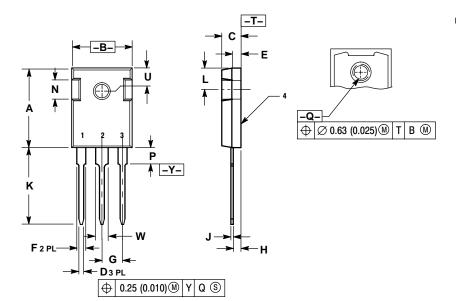


Figure 10. Thermal Response Junction to Ambient (Per Leg)

PACKAGE DIMENSIONS

TO-247 PSI PLASTIC CASE 340L-02 ISSUE D



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	20.32	21.08	0.800	8.30
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Е	2.20	2.60	0.087	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	20.06	20.83	0.790	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
Р		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

STYLE 2: PIN 1. ANODE

- 2. CATHODE (S) 3. ANODE 2
- 4. CATHODES (S)

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